

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Dresden Fab Transfer for D2Pak Package

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **10-September-2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhober
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Dresden Fab Transfer for D2Pak Package

► **Products affected:**

Sales Name	SP N°	OPN	Package
IRFS3004PBF	SP001557216	IRFS3004PBF	D2PAK
IRFS3006PBF	SP001568064	IRFS3006PBF	D2PAK
IRFS3107PBF	SP001573388	IRFS3107PBF	D2PAK
IRFS4010PBF	SP001578304	IRFS4010PBF	D2PAK
IRFS4510TRLPBF	SP001557402	IRFS4510TRLPBF	D2PAK

► **Detailed Change Information:**

Subject: Add Dresden 300MM as qualified Fab for Gen 10.7 D2Pak products

Reason: Expansion of wafer production and wafer test capacity.

Description: Dresden Fab Transfer for D2Pak Package

Site	Old	New
Fab	Vanguard International Semiconductor or	Infineon Technologies AG, Dresden, Germany or
Fab	Infineon Technologies Newport Limited	Vanguard International Semiconductor or
Fab		Infineon Technologies Newport Limited

► **Product Identification:** Wafer fab origins will not be distinguished through the external part marking or shipping labels, however, based on the assembly lot code and marked on the device. IFX internal systems will be able to trace the site of the wafer lots used to produce the final product.

► **Impact of Change:** No changes to form, fit, or function. The package outline remains the same. Datasheet specifications will not be changed. The package bill of material and the location for assembly and final test will not change.

► **Attachments:**

► **Time Schedule:**

- Final qualification report: available
- First samples available: on request

Process / Product Change Notification



N° 960-CUST90-C4048408-Private

■ Intended start of delivery:

09-November-2016

If you have any questions, please do not hesitate to contact your local Sales office.